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# **Contents**

v vii	Authors Conference Committee
	BIOMEDICAL IMAGING USING A DMD OR OTHER MEMS ARRAY: JOINT SESSION WITH 11243 AND 11294
11294 02	Digital micromirror device based angle-multiplexed optical diffraction tomography for high throughput 3D imaging of cells [11294-1]
11294 03	A high throughput synthetic aperture phase microscope [11294-2]
	BIOMEDICAL FABRICATION USING A DMD OR OTHER MEMS ARRAY: JOINT SESSION WITH 11243 AND 11294
11294 05	DMD-based rapid 3D bioprinting for precision tissue engineering and regenerative medicine (Keynote Paper) [11294-4]
	ADVANCED MANUFACTURING USING A DMD OR OTHER SLM: JOINT SESSION WITH 11292 AND 11294
11294 07	Rapid prototyping MEMS with laminated resin printing (Invited Paper) [11294-6]
11294 08	Curing subpixel structures for high-resolution printing of translucent materials using standard DLP-projectors [11294-7]
	BEAM SHAPING
11294 OB	Complex wavefront manipulation and holographic correction based on digital micromirror device: a study of spatial resolution and discretisation [11294-10]
11294 OC	Angular and spatial light modulation by single digital micromirror device for beam and pattern steering (Best Student Paper Award) [11294-11]
11294 0D	New Fourier CGH coding using DMD generated masks [11294-12]

#### **NOVEL AND ADVANCED APPLICATIONS**

11294 0G	Innovations with a massively paralleled, microelectromechanical systems (MEMS) toward piston-mode-based phase light modulator (PLM) [11294-15]
11294 OH	Single DMD intelligent headlight with LiDAR [11294-16]
11294 01	Further investigation of the effects of total ionizing dose on digital micromirror devices [11294-17]
	AR/VR DISPLAYS USING DMDS OR OTHER SLM DEVICES: JOINT SESSION WITH 11294 AND 11304
11294 OK	Projector-based augmented reality with simultaneous 3D inspection using a single DMD (Best Paper Award) [11294-19]
11294 OL	Augmented reality, 3D measurement, and thermal imagery for computer-assisted manufacturing [11294-20]
11294 OM	Optical calibration and distortion correction for a volumetric augmented reality display [11294-21]
	3D METROLOGY
11294 00	Structured-light systems using a programmable quasi-analogue projection subsystem [11294-23]
11294 OP	Digital image correlation for highly reflective objects using digital micro-mirror device [11294-24]

### **Authors**

Numbers in the index correspond to the last two digits of the seven-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first five digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Baker, James C., 0G Bartlett, Terry A., 0G Bauckhage, Y., 08 Belashov, Andrey V., 0B Bertarelli, Chiara, 0D Best, Andrew D., 07 Bianco, Andrea, 0D Boisvert, Jonathan, 0K, 0L, 0O Bubendorfer, Andrea J., 07 Carts, Martin, 0I

Carts, Martin, 0I Chang, Yung Peng, 0H Chen, Shaochen, 05 Choi, Heejoo, 0C Dicaire, Louis-Guy, 0K, 0O

Drouin, Marc-Antoine, 0K, 0L, 0O

Fuchs, Henry, 0M

Georgieva, Alexandra O., 0B

Glasson, Neil D., 07 Godin, Guy, 0K, 0L, 0O Hall, James N., 0G He, Yanping, 02 Heinrich, A., 08

Hellman, Brandon, OC

Irwin, Alexis, 01 Jones, Harrison B., 07 Lanzoni, Patrick, 0D

Li, Beiwen, OP Li, Kenneth, OH

Luo, Chuan, 0C

McDonald, William C., 0G

Moore, Ciaran P., 07 Ninkov, Zoran, 01

Oden, Patrick I., 0G

Oggioni, Luca, 0D

Oram, Kathleen, Ol

Pariani, Giorgio, 0D

Petrov, Nikolay V., 0B

Picard, Michel, 0K, 0L, 0O

Rathinavel, Kishore, OM

Rodriguez, Joshua, OC

Sun, Bingjie, 05

Suresh, Vignesh, OP

Takashima, Yuzuru, OC

Vorobiev, Dmitry, 01

Wang, Hanpeng, 0M

Wang, Yijin, 02

Wei, Shiyuan, 03

Xiao, Yi, 03

You, Shangting, 05

Yu, Claire, 05 Zamkotsian, Frederic, 0D Zhou, Renjie, 02, 03 Zhu, Wei, 05

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Biomedical Imaging Using a DMD or Other MEMS Array: Joint Session with 11243 and 11294

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4 3D Lithography with DMD and SLM Devices: Joint Session with 11292 and 11294

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**Ganapathy Sivakumar**, Texas Instruments Inc. (United States)

5 Beam Shaping

John Ehmke, Texas Instruments Inc. (United States)

6 Novel and Advanced Applications **Benjamin L. Lee**, Texas Instruments Inc. (United States)

7 AR/VR Displays Using DMDs or other SLM Devices: Joint Session with 11294 and 11304

**Alex Lyubarsky**, Texas Instruments Inc. (United States) **Hong Hua**, Wyant College of Optical Sciences (United States)

8 3D Metrology

Roland Höfling, ViALUX GmbH (Germany)